TSG-RAN Working Group 1 Meeting #14 ***TSGR1#14(00)0956***
Oulu, Finland, July 4-7, 2000

Title: Draft LS to WG2, WG3, and WG4: Status Report of the WI ‘Low Chip Rate TDD, physical layer’ and request for support

Source: TSG-RAN WG1

To: TSG-RAN WG2, TSG-RAN WG3, TSG-RAN WG4

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TSG RAN WG1 as the leading working group has begun the work for the release 2000 work items ‘Low Chip Rate TDD, physical layer’ and ‘Low chip rate TDD’, according to RP-000191 and RP-000311. This LS intends to inform the other groups about the current situation in TSG RAN WG1 and the impacts on the other groups as they are seen by TSG RAN WG1.

In order to summarize the overall concept of the physical layer of the Low Chip Rate TDD, TSG RAN WG1 has set up the technical report TR25.928, which was noted in RAN#8 meeting as version 1.0.0. This technical report describes the 1.28 Mcps functionality as it is currently considered in WG1 and it highlights the commonalties and differences between the two TDD options.

Based on this technical report, TSG RAN WG1 has collected the items, where support is possibly needed by TSG RAN WG2, WG3, and WG4, respectively. These items are given in the attached table.

In order to proceed with the work item according to the time schedule decided in RAN#8, TSG RAN WG1 would appreciate an answer regarding the support at the beginning of the next TSG RAN WG1 meeting, 22-25 august.

Impacts to
WG2_3_4_DRAFT.dc